

-FORM PTO-1449 (Modified)	ATTY. DOCKET NO. BU9-97-224B	SERIAL NO. 5442
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	APPLICANT: P. Hongsinger et al.	09/678,742
(Use several sheets if necessary)	FILING DATE: Concurrently	GROUP: 2825 Unassigned

992 09/678,742 PRO 04/00

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

EXAMINER INITIALS	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPRO.)
W	5,430,602	2-3-93	7195 Chin et al.			
	5,637,900	2-6-95	10197 Ker et al.			
	5,610,427	4-22-96	3197 Shida			
	5,063,429	9-17-90	11191 Crafts			

FOREIGN PATENT DOCUMENTS

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

W	A. G. George, et al., "Packaging Alternatives to Large Silicon Chips: Toled Silicon on MCM and PWB Substrates", IEEE, 1996, pp. 699-708.
	M. Ker, et al., "Whole-Chip ESD Protection Design for Submicron CMOS VLSI", IEEE, June 1997, pp. 1920-1923.
	P. Zuchowski, et al., "I/O Impedance Matching Algorithm for High-Performance ASICs", ASIC 1997 Conference. no page #s
	B. Basaran, et al., "Latchup-Aware Placement and Parasitic-Bounded Routing of Custom Analog Cells", IEEE, 1993, pp. 415-421.
	J. Easton, et al., "A System Engineering Approach to Design of On-Clip Electrostatic Discharge Protection", IEEE, 1996, pp. 22-28.
	B. Rodgers, et al., "Attacking ESD", Circuits Assembly, June 1995, p. 40 only.
	S. Beebe, "Methodology for Layout Design and Organization of ESD Protection Transistors", EOS/ESD Symposium, 1996, pp. 265-275.
	W. Russell, "Defuse the Threat of ED Damage", Electronic Design, March 6, 1995, p. 115 only.
	C. Duvury, et al., "ESD: A Pervasive Reliability Concern for IC Technologies", Proceeding of the IEEE, Vol. 81, No. 5, May 1993, pp. 690-702.
	Jim Lipman, "Postlayout EDS Tools Lock Onto Full-Chip Verification", EDN, October 10, 1996, pp. 93-104.

EXAMINER

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DATE CONSIDERED

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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.